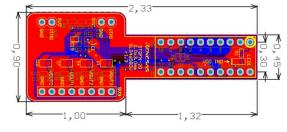


# 1. Description

The GreenPAK DIP Adapter is a small PCB that lets you adapt STQFN packages into a DIP footprint. This board can speed up your design prototyping and testing. This small board 0.90x2.33 inch uses 20 pins DIP footprint with 0.3 inch width. You can also use this adapter for prototyping by making TQFN package compatible with solder free breadboards.

## 2. Features

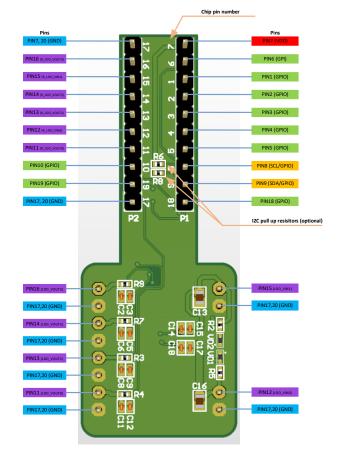
- Low cost
- Simplifies prototyping of SMT IC's
- Optional V<sub>DD</sub> LED indicator
- Decoupling capacitor included
- Optional I<sup>2</sup>C pull-up resistors



Note 1 All sizes in inches.

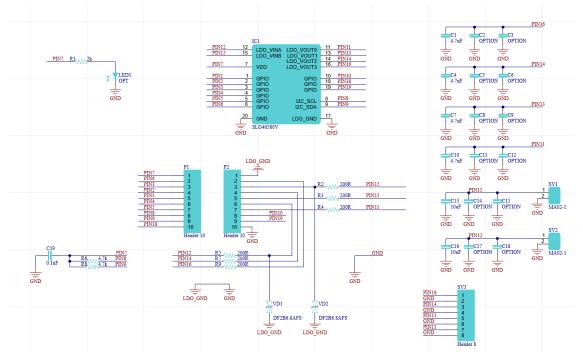
#### 3. Top View LED current limit resistor (optional) VDD LED indicator (optional 0 G LED1 RI G PIN6 (GPI) Ð G PIN1 (GPIO) 0 G PIN2 (GPIO) Ð DNI DOM 0 G PIN3 (GPIO) 0 G PIN4 (GPIO) 6 0 PIN5 (GPIO) 6 0 PIN8 (SCI /GPIO) PIN10 (GPIO) 0 0 PIN19 (GPIO) PIN9 (SDA/GPIO) 0 C PIN18 (GPIO) Chip package type Chip package numbe 20 VOUT3 PIN15 . GND GND 1 GreenPAK chip IC1 VOUT2 VDD Chip decoupling capacitor GND 10 **P**4 C19 VOUT1 GND . VINO VOUTO PIN12 (LDG GND GND

# 4. Bottom View





# 5. Board Schematic



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